



Model-Based Synthesis of High-Speed Serial-Link Transmitter Designs

Ikchan Jang¹, Soyeon Joo¹, SoYoung Kim¹, Jintae Kim²,

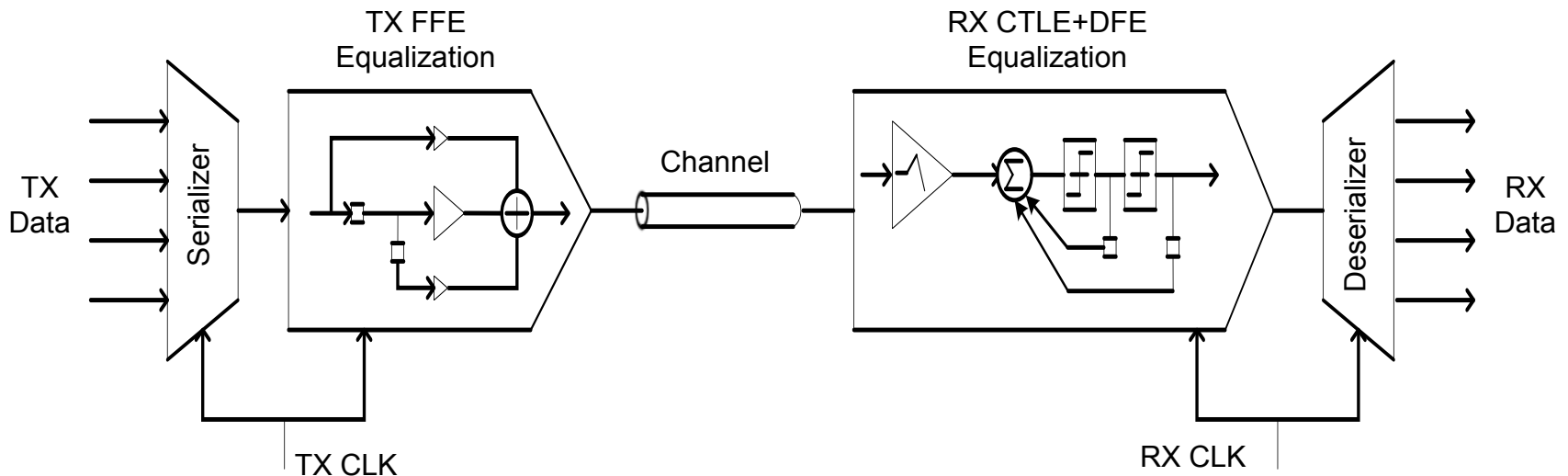
¹College of Information and Communication Engineering,
Sungkyunkwan University, Suwon, Korea

²Department of Electronics Engineering, Konkuk University,
Seoul, Korea

Outline

- Introduction
 - High-Speed Serial-link transmitter
 - Geometric Programming (GP)
- Model-based Design Framework(CML)
 - Transistor Level Modeling
 - Circuit Level Modeling
 - Numerical Experiments for Model Validation
 - Hierarchical Modeling
- System Level Optimization
- Conclusion

Introduction



- High-speed links are common building blocks in consumer electronics.
- Many link systems are designed using current-mode logic(CML) circuits.
 - CML Buffer, Latch, Multiplexer...
- Lack of automated design flow prohibits efficient design reuse of links
- Our goal: To provide an design synthesis flow for CML-style circuits

Introduction

- **Geometric programming (GP)**

minimize $f_o(x)$

subject to $f_i(x) \leq 1, \quad i = 1, \dots, m$
 $g_i(x) = 1, \quad i = 1, \dots, p$

where f_i are posynomials, g_i are monomials

monomial : $g(x) = cx_1^{\alpha_1}x_2^{\alpha_2} \dots x_n^{\alpha_n}$ with $c > 0, \alpha_i \in \mathbb{R}$

posynomial : $f(x) = \sum_{k=1}^N c_k x_1^{\alpha_{1k}} x_2^{\alpha_{2k}} \dots x_n^{\alpha_{nk}}$ with $c_k > 0, \alpha_{ik} \in \mathbb{R}$

- **Model-based synthesis via geometric programming[1][2]**

- Computationally efficient
- Scalable to a hierarchical design with inter-block dependency
- Seamless design porting over process and technology
- Challenge: accurate circuit-level model compatible with GP

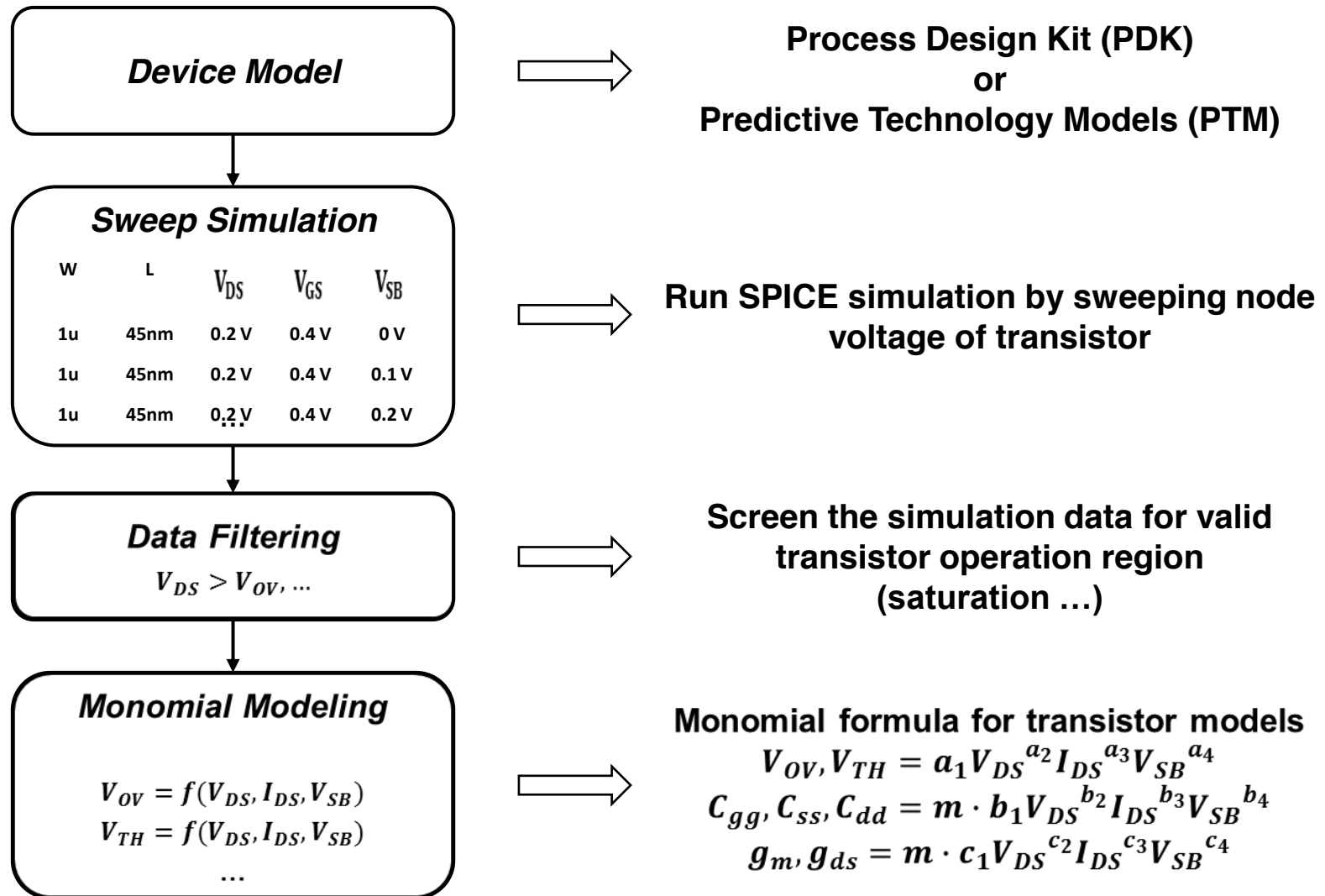
[1] M. Hershenson, et al, "Optimal design of a CMOS opamp via geometric programming," IEEE TCAD. 2001

[2] D. M. Colleran, et al, "Optimization of phase-locked loop circuits via geometric programming," CICC2003.

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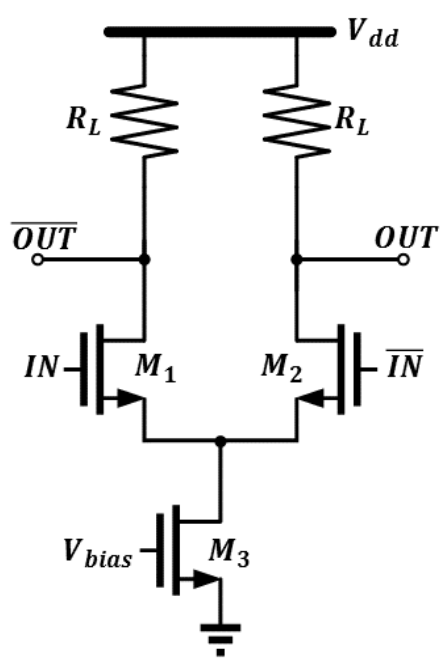
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Transistor Level Modeling

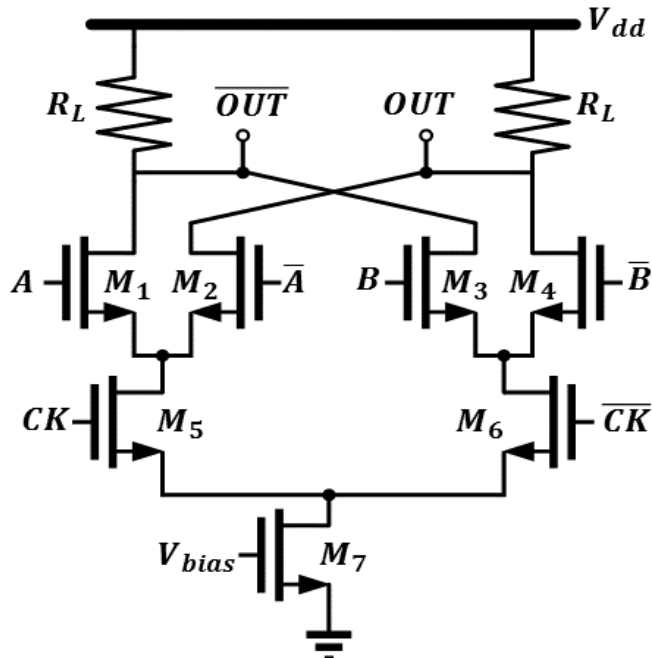


[3] J. Kim, et al, "Convex piecewise-linear modeling method for circuit optimization via geometric programming," IEEE TCAD. 2010

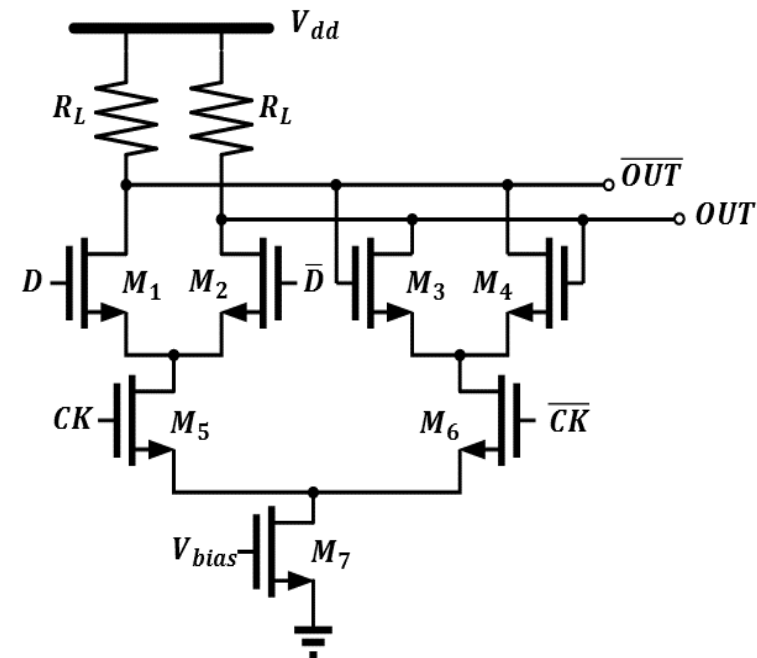
Circuit Level Modeling



Buffer



MUX



Latch

- CML-circuit models should include
 - Bias constraints: to ensure full-steering of bias current
 - Delay models: to estimate propagation delay

Bias constraints

Dimension constraints

$$W_1 = W_2, L_1 = L_2 = L_{min}$$

...

Bias modeling

$$I_1 = I_2 = 0.5I_3$$
$$V_{OV3} + V_{TH3} \leq V_{bias}$$
$$V_{DS3} + V_{OV1} + V_{TH1} \leq V_{icm}$$
$$V_{DS3} + V_{DS1} + 0.5I_3R_L \leq V_{dd}$$

...

Performance parameters

$$A_v = g_{m1}R_L$$
$$Power = V_{dd} \times I_3$$
$$Area = 2\alpha_0R_L + \alpha_1\sum_{i=1}^N W_iL_i$$
$$\tau = R_L(C_L + C_{dd1}) + (C_{ss1} + C_{dd3})/g_{m3}$$

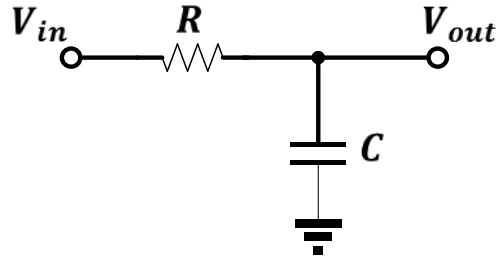
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Operating conditions

$$V_{OV1} \leq V_{DS1}, V_{OV3} \leq V_{DS3}$$
$$\sqrt{2}V_{OV1} \leq V_{id}$$

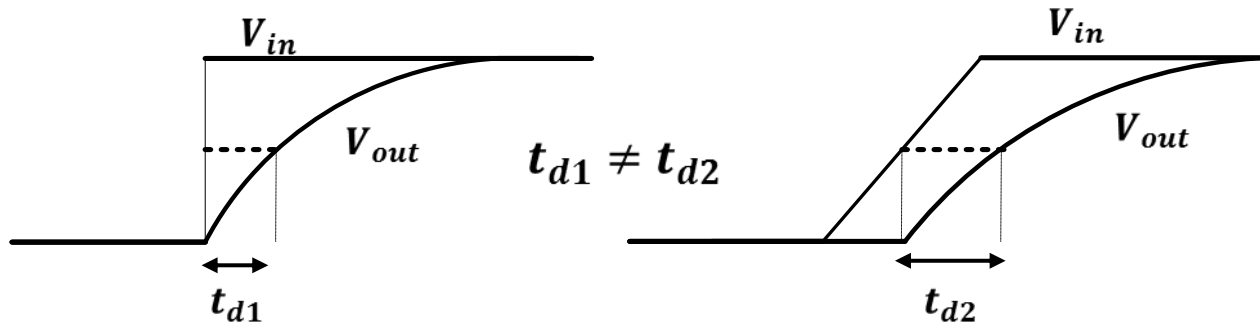
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CML Gate Delay Model



$$t_d = \ln(2) \cdot \tau \approx 0.6933\tau = 0.6933RC$$

- Simple RC delay model cannot reflect practical signal transition in high-speed serial-link systems[4].
- Finite input slope effects should be included in delay models.

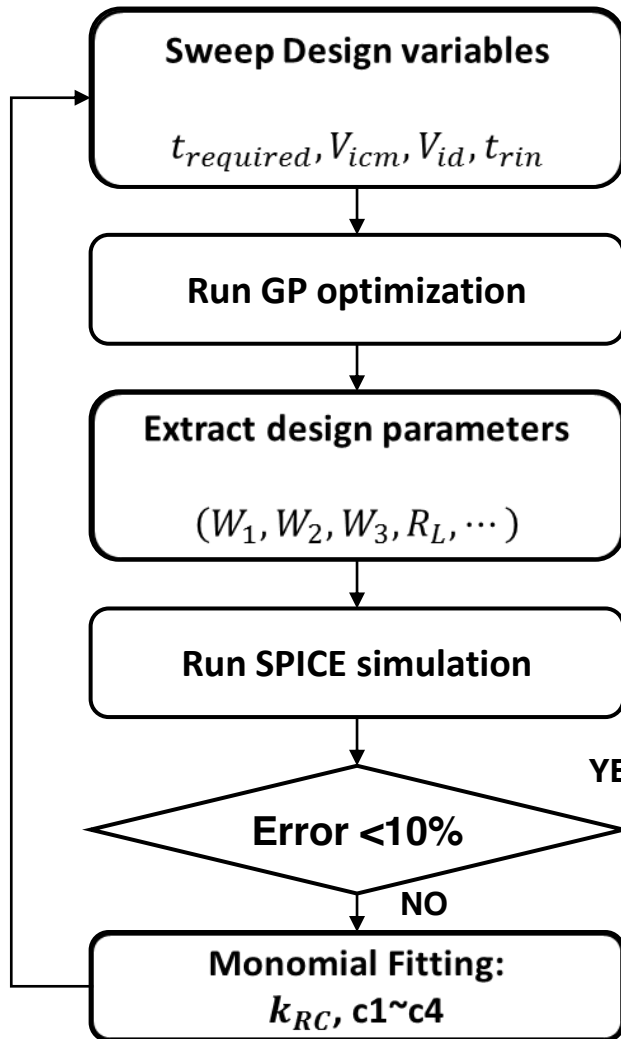


- Earlier CML gate delay models[5] do not have GP compatible forms.

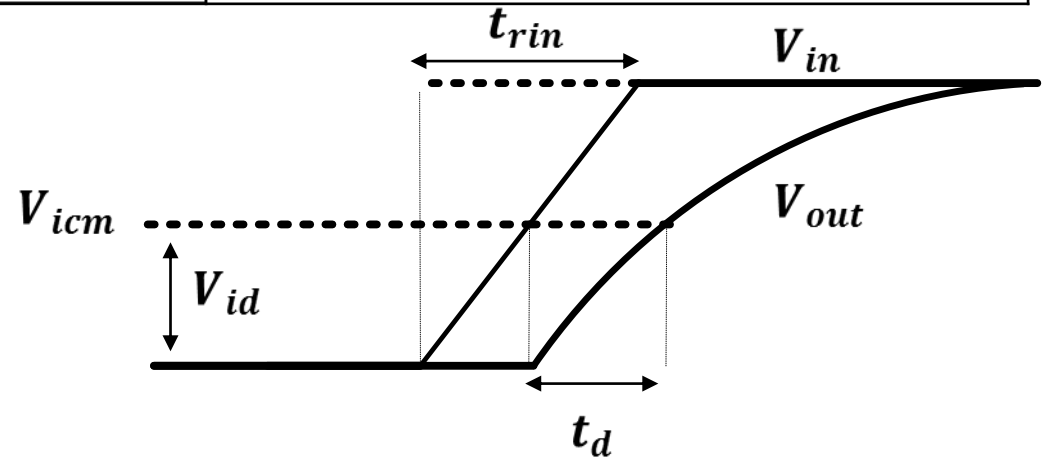
[4] H. Hassan, et al, "MOS current mode circuits: Analysis, Design and Variability," IEEE TVLSI 2005

[5] U. Seckin, et al, "A Comprehensive Delay Model for CMOS CML Circuits," IEEE TCAS. I . 2008

CML Gate Delay Model



Variables	Description
$t_{required}$	Timing margin
V_{icm}	Input CM voltage
V_{id}	Input differential voltage
t_{rin}	Input rise time



$$t_d = k_{RC}\tau = c_1 V_{id}^{c_2} t_{required}^{c_3} t_{rin}^{c_4} \tau$$

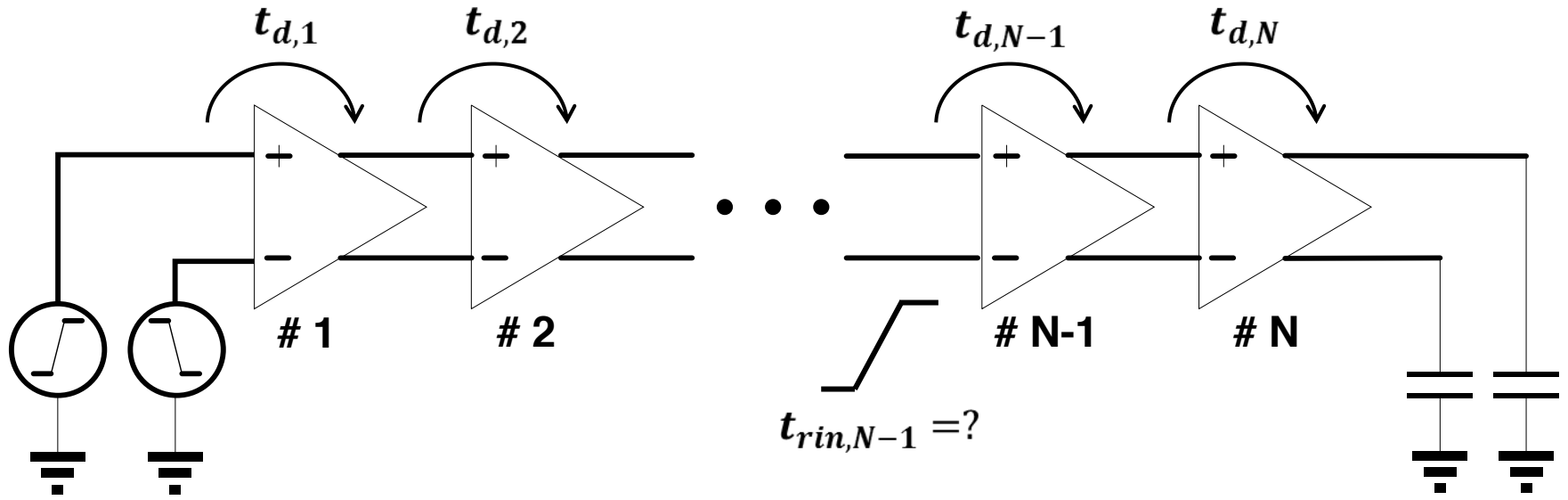
($c_1 \sim c_4$: fitting parameters of delay model)

[6] S. Y. Kim, et al, "Closed-form RC and RLC delay models considering input rise time," IEEE TCAS. I . 2007

[7] R. Mita, et al, "Propagation delay of a RC chain with a ramp input," IEEE TCAS. II . 2007

CML Gate Delay Model

- Output rise time models

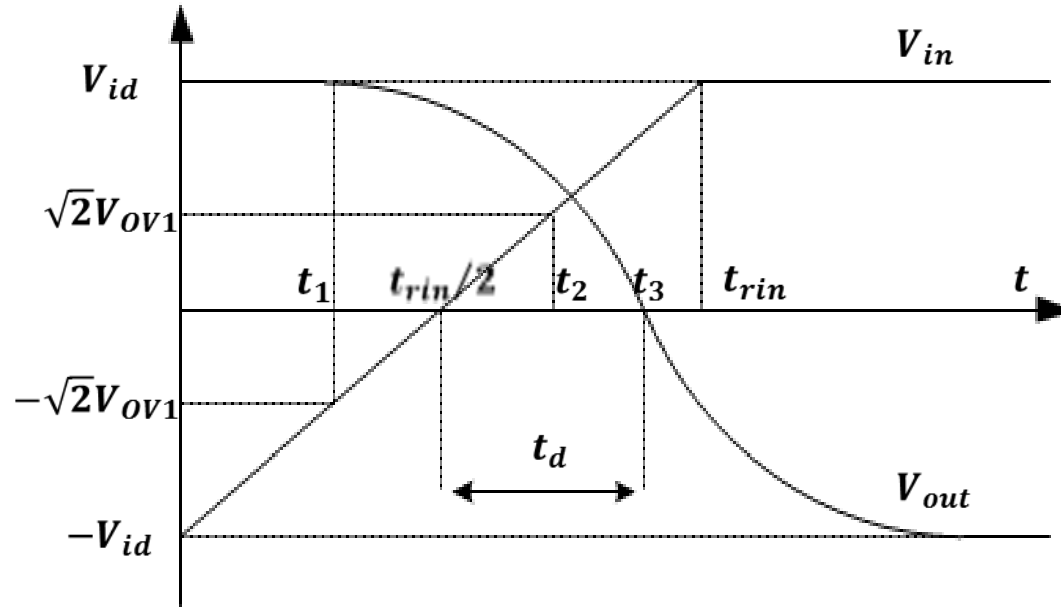


Newly proposed delay model need exact input rise time

- For design synthesis of cascaded CML-based circuits, output rise time should be estimated.

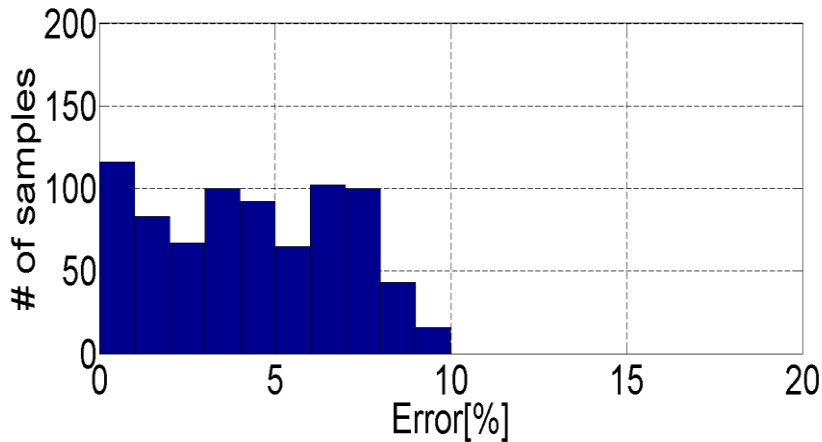
CML Gate Delay Model

- Output rise time models

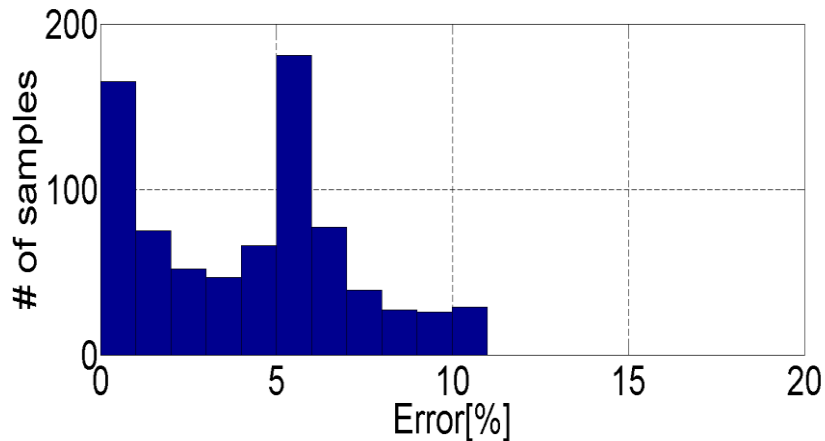


$$\begin{aligned}
 t_{rout} &= 2(t_3 - t_1) = 2 \left(t_3 - \frac{1}{2}t_{rin} + \frac{1}{2}t_{rin} - t_1 \right) \\
 &= 2 \left(t_d + \frac{\sqrt{2}V_{OV1}}{2V_{id}} t_{rin} \right) \approx a_1 \left(\frac{\sqrt{2}V_{OV1}}{2V_{id}} t_{rin} \right)^{a_2} t_d^{a_3}
 \end{aligned}$$

Numerical Simulation for Model Validation



(a)



(b)

Modeling error statistics of CML buffer

(a) t_d (b) t_{rout}

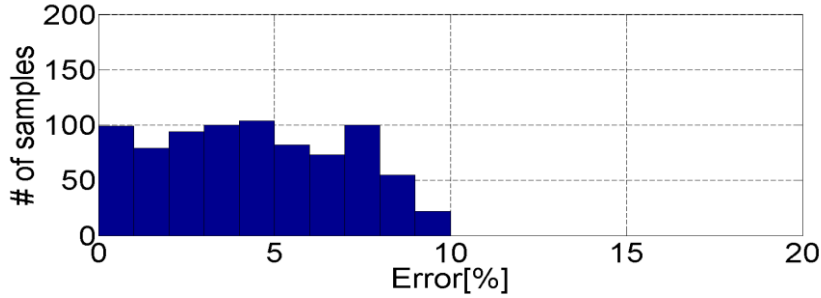
Process Design Kit(PDK)

– Predictive Technology Model 45nm

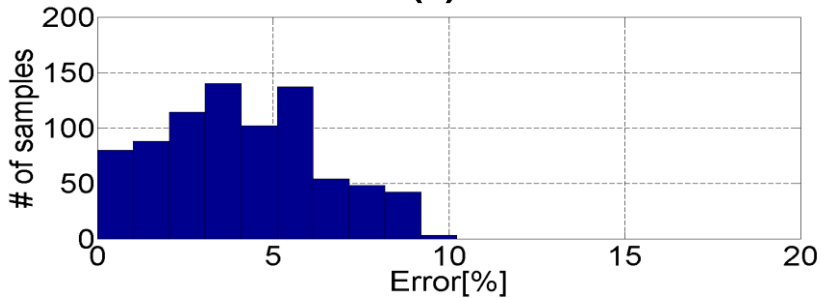
Mean/Max modeling error of CML buffer

Variable /Sweep Range	$V_{icm} = [0.8, 0.95]$, $V_{id} = [0.3, 0.15]$ $t_{required} = [10 \text{ ps}, 100 \text{ ps}]$ $t_{rin} = [10 \text{ ps}, 300 \text{ ps}]$
Property	Mean/Max modeling error[%]
t_d	4.34/10.00
t_{rout}	4.23/11.00

Numerical Simulation for Model Validation

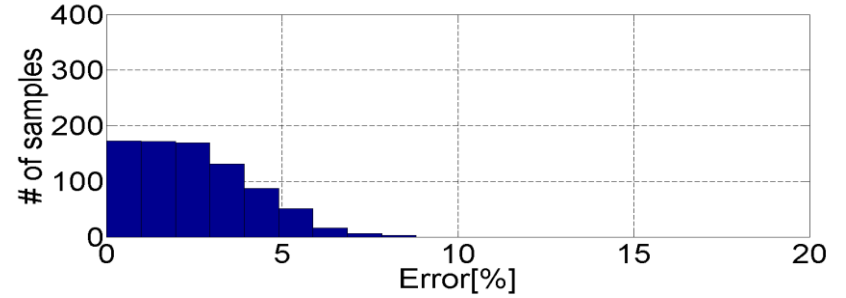


(a)

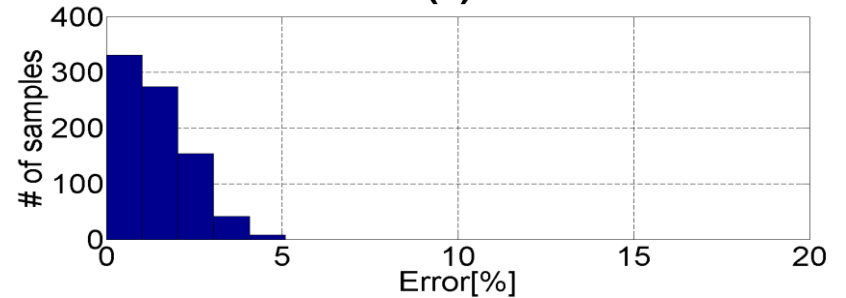


(b)

Modeling error statistics of CML multiplexer (a) t_d (b) t_{rout}



(a)



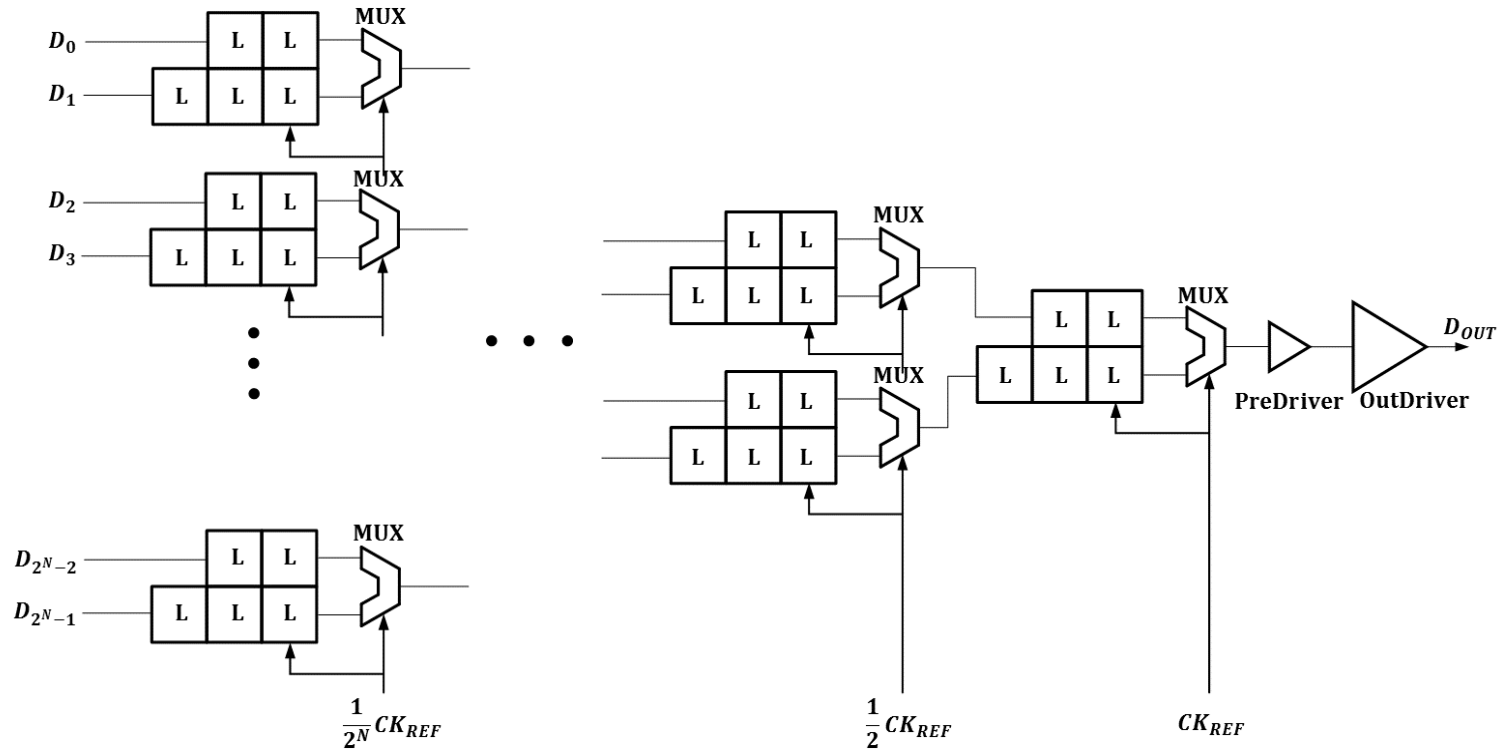
(b)

Modeling error statistics of CML latch (a) $t_{rout,c2q}$ (b) $t_{rout,d2q}$

Property	Mean/Max modeling error[%]
t_d	4.45/10.00
t_{rout}	4.11/10.22

Property	Mean/Max modeling error[%]
$t_{rout,c2q}$	2.48/8.82
$t_{rout,d2q}$	1.40/5.09

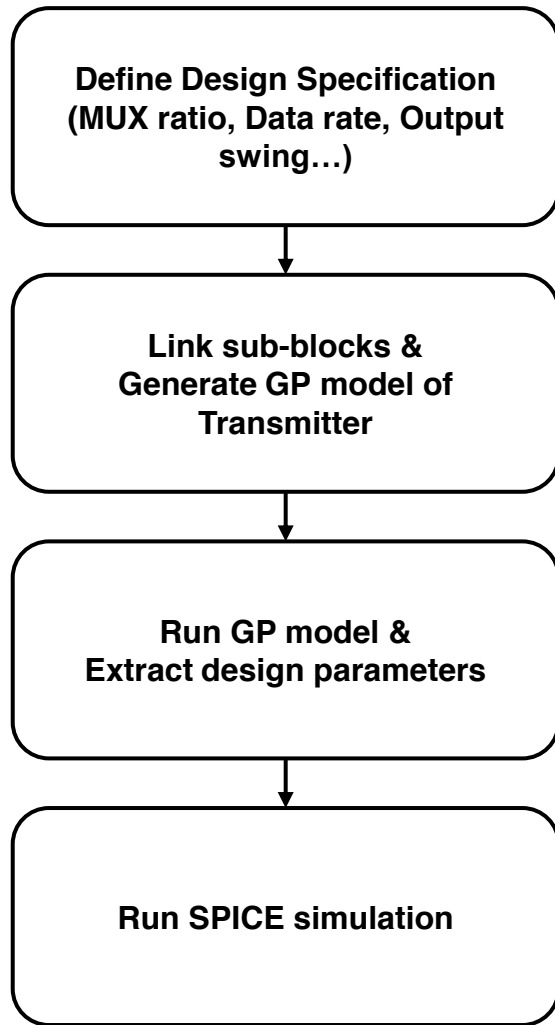
Hierarchical Modeling



Architecture of transmitter with $2^N:1$ serializer

- To use unit CML gates as standard cell, dependency of all adjacent inter-nodes should be considered: capacitance loading, voltage swing

Hierarchical Modeling



Variables	Description
N	Number of stage
DR	Data rate
$V_{out,min}$	Minimum single-ended output voltage swing
$Area_{max}$	Maximum area allowed for design
C_{out}	Final output load capacitance

```

for k=1:N do
  Cload.latch(k)==Cin.mux(k)
  Vin_swing.mux(k)==Vout_swing.latch(k)
  if n≠N then
    Cload.mux(k)==Cin.latch(k+1)
    Vin_swing.latch(k+1)==Vout_swing.mux(k)
  end if
end for
Cload.mux(N)==Cin.predriver
Cload.predriver=Cin.outdriver
Cload.outdriver=Cout
Vin_swing.predriver==Vout_swing.mux(N)
Vin_swing.outdriver==Vout_swing.predriver
tin_rise.predriver==tout_rise.mux(N)
tin_rise.outdriver==tout_rise.predriver
  
```

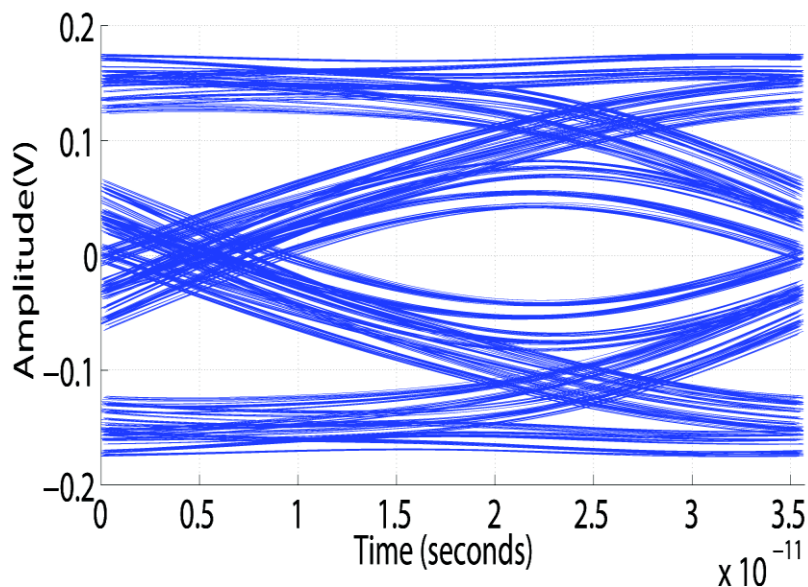
⇒ Modeling code for inter-node dependency

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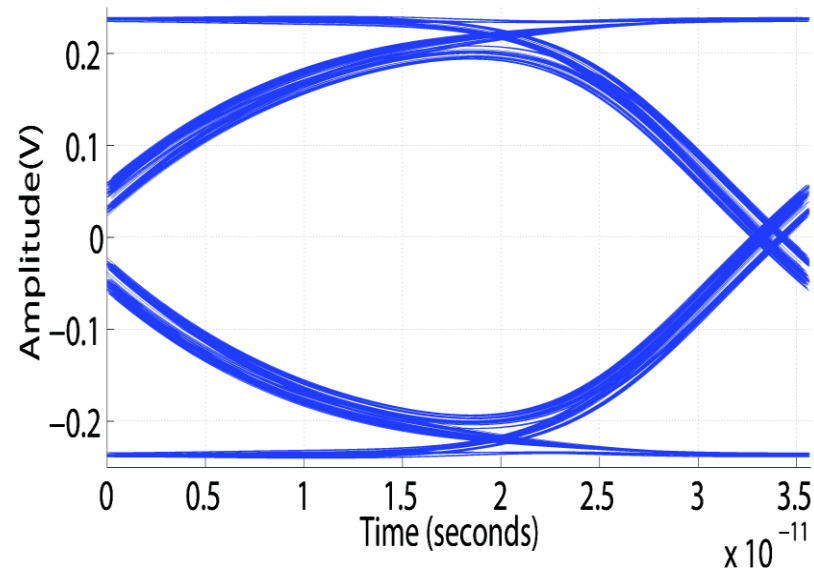
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Comparison with simple RC Model

	Design specifications
MUX ratio	8:1
Data rate	28 Gb/s
V_{ppd}	≥ 400 mV
$t_{rin,ck}/T$	0.4

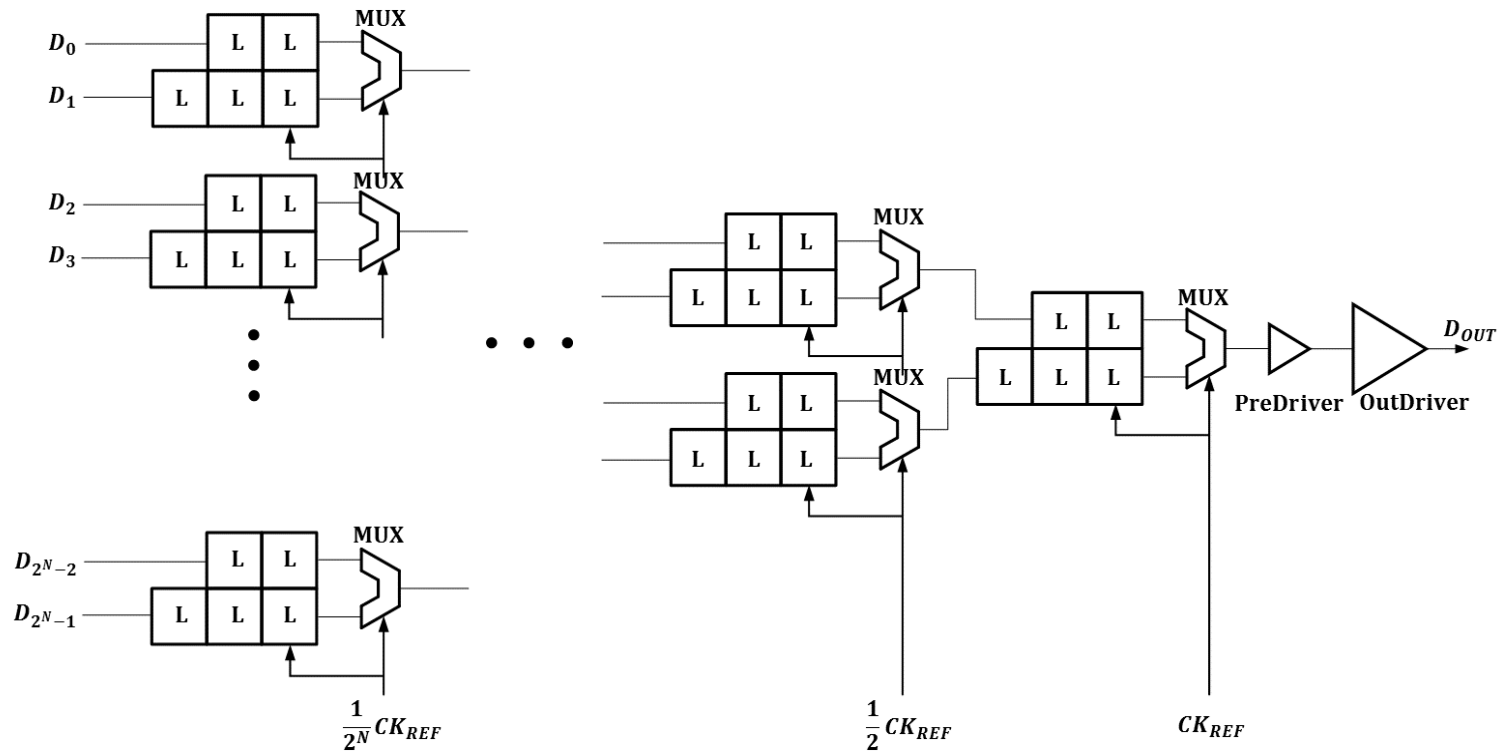


(a) Simple RC model



(b) Proposed delay model

Inter-stage voltage swing optimization



- Various design techniques for improving power efficiency can be easily explored at the top-level model.
 - Example: can we improve power efficiency of I/O by using variable inter-stage voltage swing?

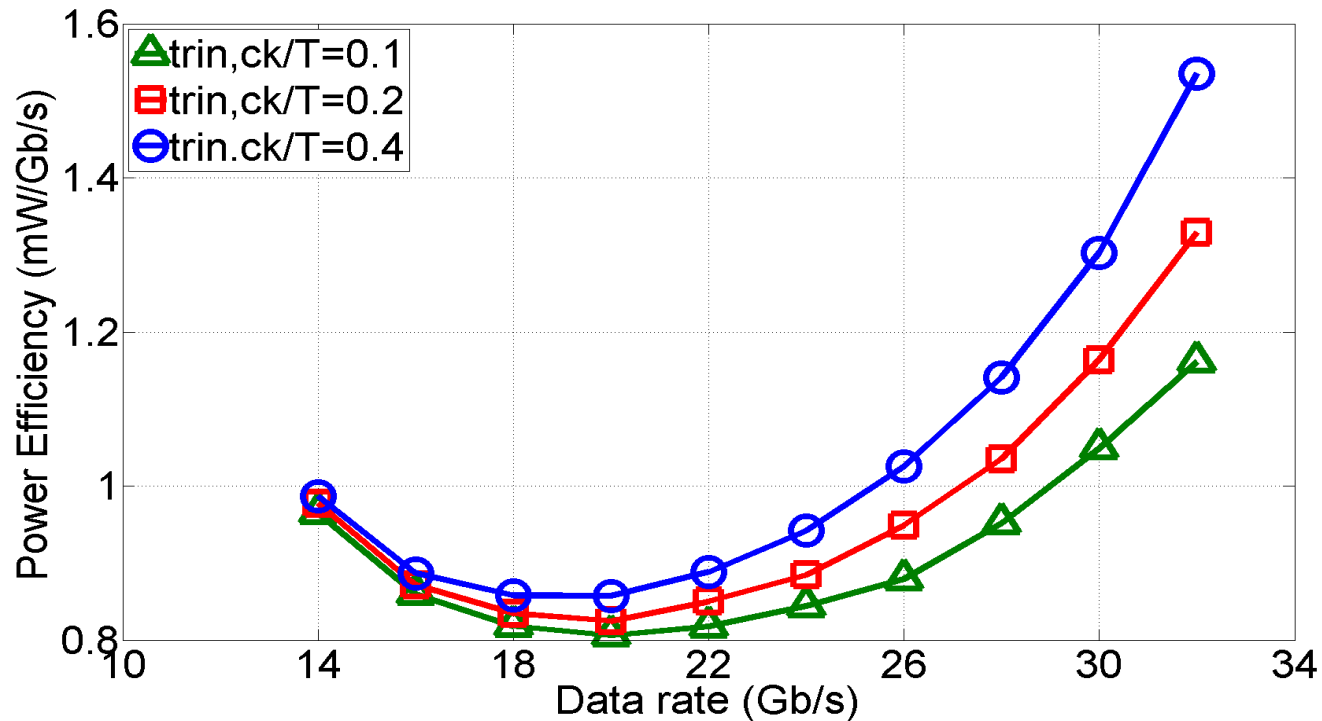
Inter-stage voltage swing optimization

Comparison between varying inter-stage swing and constant swing in sub-blocks at 28 Gb/s

	Variable Inter-stage swing	Constant swing
Power consumption (mW)	26.643	33.370
Power efficiency (mW/Gb/s)	0.952	1.192
Vppd (mV)	400	400
Output jitter (ps_{pp})	0.86	1.09

- **Power efficiency of the transmitter can be enhanced by using variable inter-stage swing.**
 - Signal swing and f_T are simultaneously optimized depending on the different delay constraints along the serializer chain, leading to 20% improvement in power efficiency.

Optimal Power and Data Rate

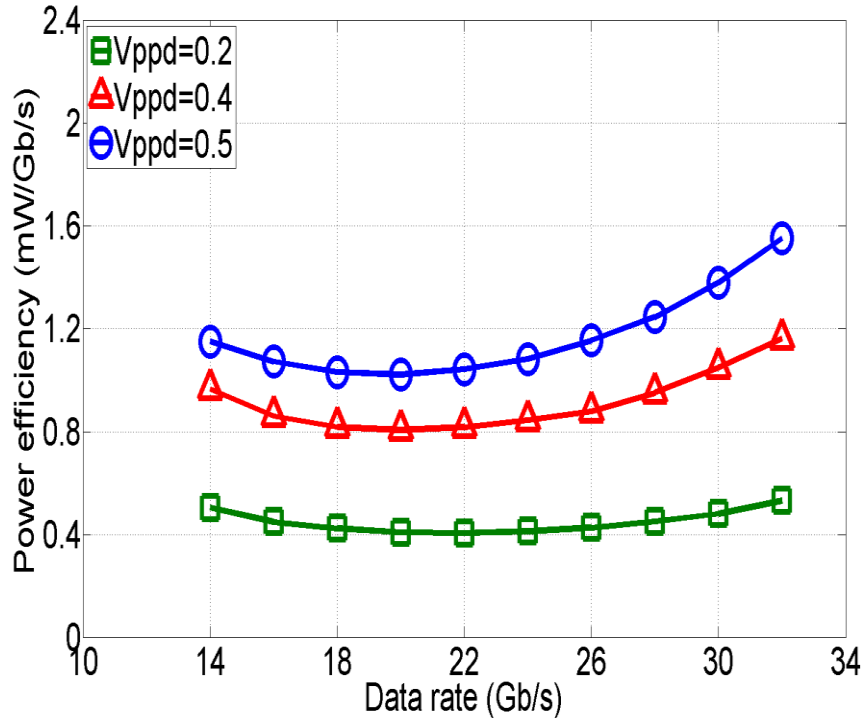


Optimal transmitter power efficiency versus data rate when $t_{r,ck}/T$ is (a) 0.1 (b) 0.2 (c) 0.4 when V_{ppd} is 400mV

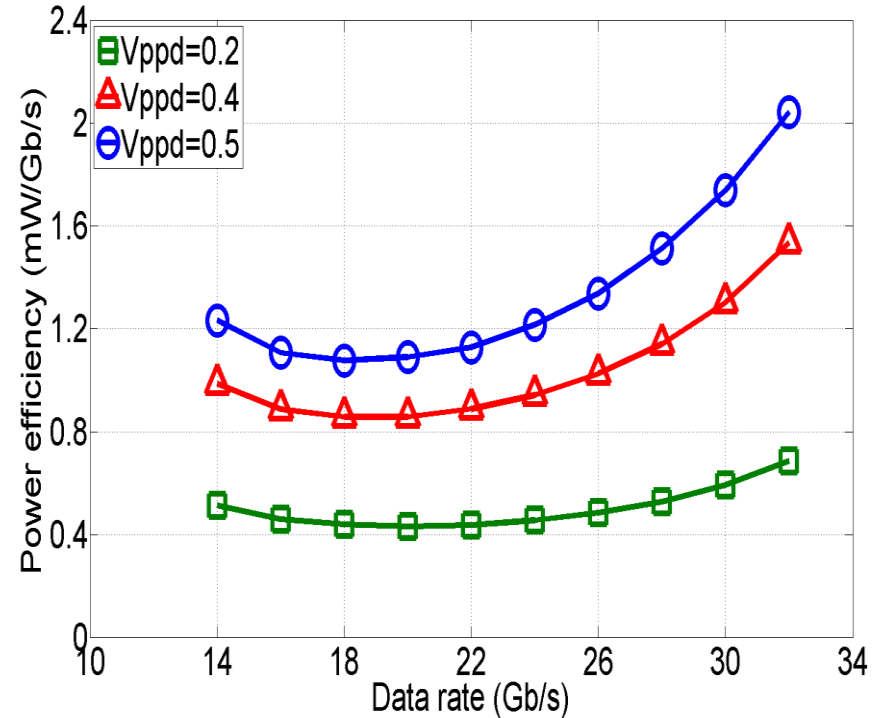
- Power penalty can be estimated by slowing down input clock transition time.
- Optimal data rate can be found to maximize power efficiency.

Optimal Power and Data Rate

$V_{ppd} \uparrow$, Clock transition time $\downarrow \Rightarrow$ Power Penalty \uparrow



(a)



(b)

Optimal transmitter power efficiency versus data rate
when $t_{rin,ck}/T$ is (a) 0.1 (b) 0.4

Conclusion

- We presented accurate CML circuit models compatible with geometric programming
- The modeling involves iterative GP optimizations to refine the accuracy, leading to ~5% mean delay modeling error
- The models can be used in a GP-compatible system-level model as demonstrated using a high-speed link transmitter
- The system-level model can be efficiently synthesized for various design specifications & processes
- Can explore intricate system-level design tradeoffs, providing valuable design guidelines

Reference

- [1] M. Hershenson, et al, “Optimal design of a CMOS opamp via geometric programming,” *IEEE Trans. Comput.-Aided Design*, vol. 20, no. 1, pp. 1-21, Jan. 2001
- [2] D. M. Colleran, et al, “Optimization of phase-locked loop circuits via geometric programming,” *Proc. IEEE Custom Integrated Circuits Conference*, 2003. pp. 377-380, 2003
- [3] J. Kim, et al, “Convex piecewise-linear modeling method for circuit optimization via geometric programming,” *IEEE TCAD*. 2010
- [4] H. Hassan, et al, “MOS current mode circuits: Analysis, Design and Variability,” *IEEE Trans. Very Large-Scale Integr. (VLSI) Syst.*, vol. 13, no. 8, pp. 885-898, Aug. 2005
- [5] U. Seckin, et al, “ A Comprehensive Delay Model for CMOS CML Circuits,” *IEEE Trans. Circuit. Syst. I . Reg. Papers.*, vol. 55, no. 9, pp. 2608-2618 Oct, 2008
- [6] S. Y. Kim, et al, “Closed-form RC and RLC delay models considering input rise time,” *IEEE Trans. Circuit. Syst. I .Reg. Papers.*, vol. 54, no.9, pp 2001-2010, Sep. 2007
- [7] R. Mita, et al, “Propagation delay of a RC chain with a ramp input,” *IEEE Trans. Circuits. Syst. II , Exp. Briefs.*, vol. 54, no. 1, pp. 66-70, Jan. 2007.

Thank You